



**/ Descriptions**

SOT-23          N    MOS                  - CHANNEL MOSFET in a SOT-23 Plastic Package.

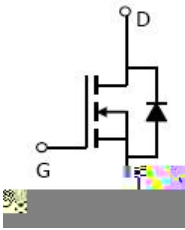
**/ Features**

$V_{DS} (V) = 30V$   
 $I_D = 5.8 A (V_{GS} = 10V)$   
 $R_{DS(ON)} < 28m (V_{GS} = 10V)$   
 $R_{DS(ON)} < 33m (V_{GS} = 4.5V)$   
 $R_{DS(ON)} < 52m (V_{GS} = 2.5V)$   
无卤产品。 HF Product.

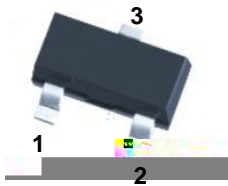
**/ Applications**

This device is suitable for use as a load switch or in PWM applications.

**/ Equivalent Circuit**



**/ Pinning**

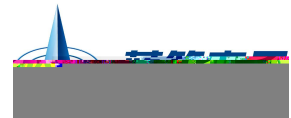


PIN1 G    PIN 2 S                  PIN 3 D

**/ Marking**

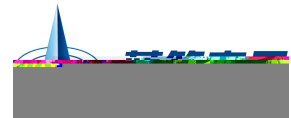
Marking	A0H
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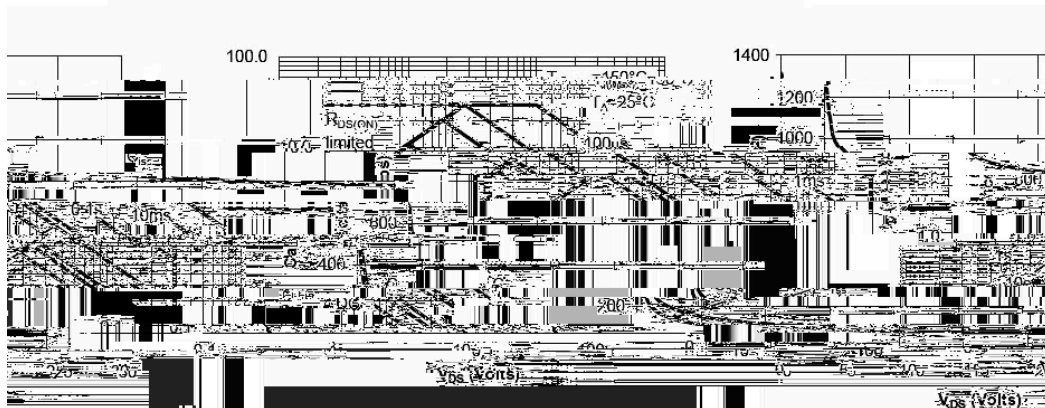
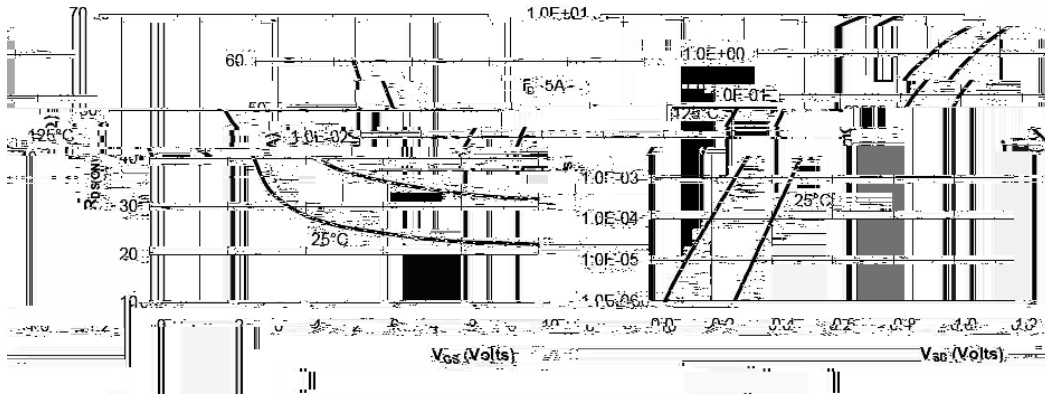
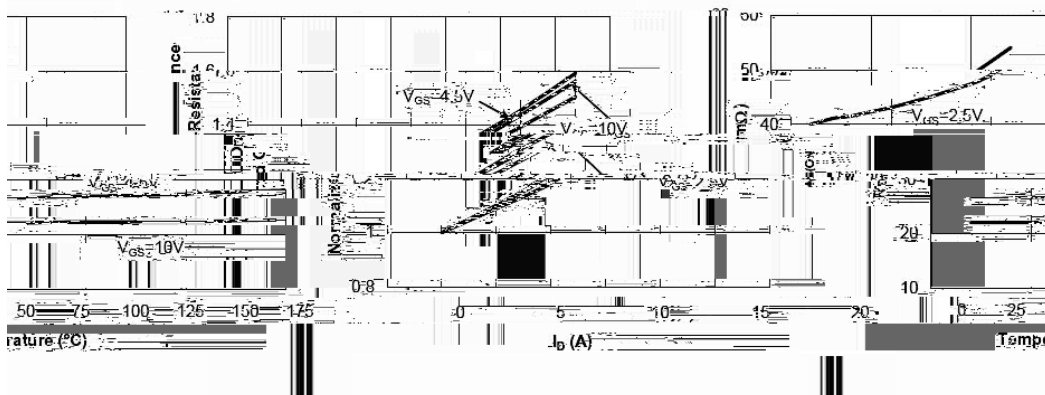
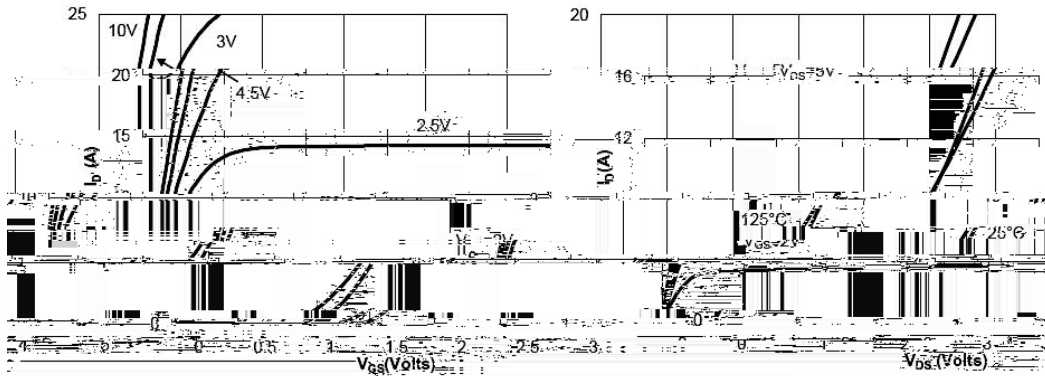


**/ Electrical Characteristics(Ta=25 )**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Capacitance	$C_{iss}$	$V_{DS}=15V$ $V_{GS}=0V$ $f=1MHz$		823	1030	pF
Output Capacitance	$C_{oss}$			99		
Reverse Transfer Capacitance	$C_{rss}$			77		
Gate resistance	$R_g$	$V_{GS}=0V$ $V_{DS}=0V,$ $f=1MHz$		1.2	3.6	
Total Gate Charge	$Q_g$	$V_{GS}=4.5V,$ $V_{DS}=15V,$ $I_D=5.8A$		9.7	12	nC
Gate Source Charge	$Q_{gs}$			1.6		
Gate Drain Charge	$Q_{gd}$			3.1		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=10V$ $R_L=2.7$ $V_{DS}=15V$ $R_{GEN}=3$		3.3	5	ns
Turn-On Rise Time	$t_r$			4.8	7	
Turn-Off Delay Time	$t_{d(off)}$			26.3	40	
Turn-Off Fall Time	$t_f$			4.1	6	
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F=5A$ $di/dt=100A/\mu s$		16	20	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$	$I_F=5A$ $di/dt=100A/\mu s$		8.9	12	nC

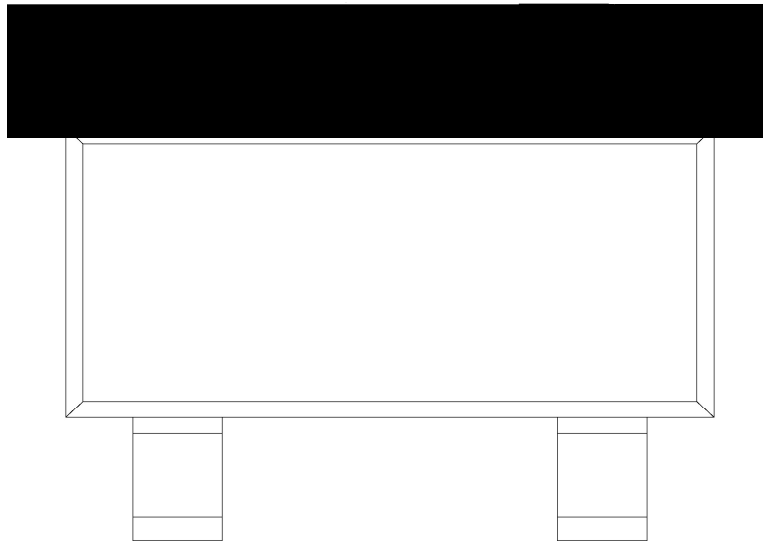


**/ Electrical Characteristic Curve**





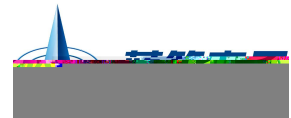
**/ Marking Instructions**



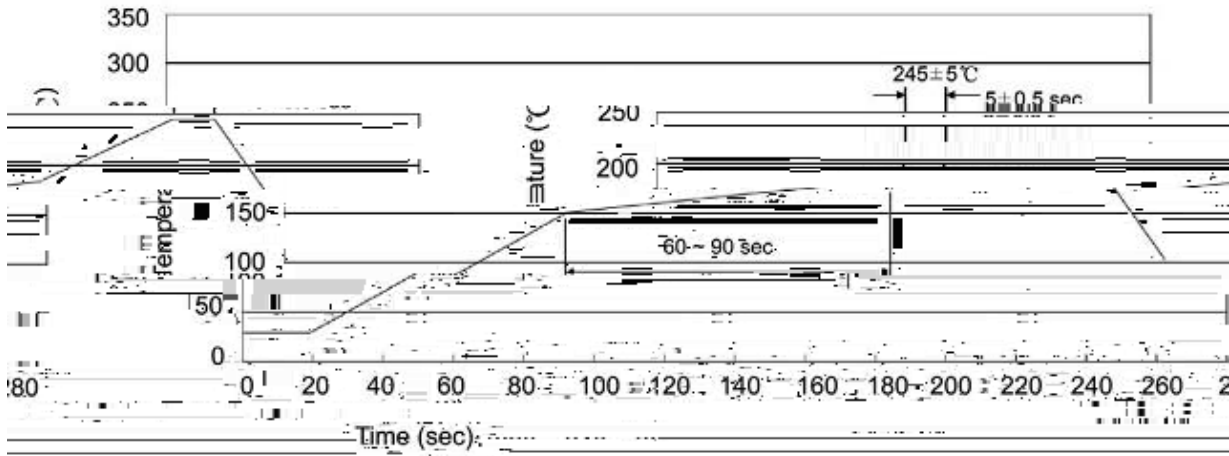
AO

H            m3NSO

Note:



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |       |     |       |          |   |
|---|-------|-----|-------|----------|---|
| 1 | 150   | 180 | 60    | 90sec;   | 1.Preheating:150~180 , Time:60~90sec.   |
| 2 | 245±5 |     | 5±0.5 | sec;     | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       |     | 2     | 10 /sec. | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260±5                      10±1 sec.                      Temp.:260±5                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type  
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